

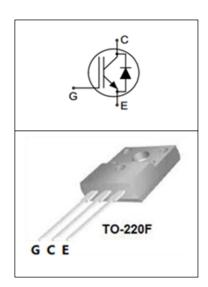
#### **IGBT**

#### **Features**

- 600V,15A
- $V_{CE(sat)(typ.)}$ =1.85 $V@V_{GE}$ =15 $V_{CE(sat)(typ.)}$ =1.85 $V_{GE}$ =15 $V_{GE}$ =15
- High speed switching
- Higher system efficiency
- Soft current turn-off waveforms
- Square RBSOA

## **General Description**

JIAEN trench IGBTs offer lower losses and higher energy efficiency for application such as IH (induction heating),UPS, general inverter and other soft switching applications.



## **Absolute Maximum Ratings**

Symbol	Parameter	Value	Units
Vces	Collector-Emitter Voltage	600	V
V <sub>GES</sub>	Gate-Emitter Voltage	<u>+</u> 20	V
I.	Continuous Collector Current ( Tc=25 °C)	30	А
Ic	Continuous Collector Current (Tc=100°C)	15	Α
Ісм	Pulsed Collector Current (Note 1)	30	А
l <sub>F</sub>	Diode Continuous Forward Current ( Tc=100 °C)	15	А
I <sub>FM</sub>	Diode Maximum Forward Current (Note 1)	30	А
t <sub>sc</sub>	Short Circuit Withstand Time	10	us
P <sub>D</sub>	Maximum Power Dissipation ( Tc=25 ℃)	28.4	W
PD	Maximum Power Dissipation ( Tc=100°C)	11.4	W
TJ	Operating Junction Temperature Range	-55 to +150	$^{\circ}$
Tstg	Storage Temperature Range	-55 to +150	$^{\circ}$

## **Thermal Characteristics**

Symbol	Parameter	Max.	Units
R <sub>th j-c</sub>	Thermal Resistance, Junction to case for IGBT	4.4	°C/ W
R <sub>th j-c</sub>	Thermal Resistance, Junction to case for Diode	5.2	°C/ W
R <sub>th j-a</sub>	Thermal Resistance, Junction to Ambient	65	°C/ W



### JNG15T60FS

## **Electrical Characteristics** (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
BV <sub>CES</sub>	Collector-Emitter Breakdown Voltage	$V_{GE}$ = 0V, $I_{C}$ = 250uA	600	-	-	V
I <sub>CES</sub>	Collector-Emitter Leakage Current	$V_{CE} = 600V, V_{GE} = 0V$	-	-	100	uA
	Gate Leakage Current, Forward	$V_{GE}$ =20V, $V_{CE}$ = 0V	-	-	100	nA
I <sub>GES</sub>	Gate Leakage Current, Reverse	V <sub>GE</sub> = -20V, V <sub>CE</sub> = 0V	-	-	-100	nA
$V_{\text{GE(th)}}$	Gate Threshold Voltage	$V_{GE} = V_{CE}$ , $I_{C} = 250uA$	4.5	-	6.5	V
$V_{CE(sat)}$	Collector-Emitter Saturation Voltage	V <sub>GE</sub> =15V, I <sub>C</sub> = 15A	-	1.85	2.2	V
Qg	Total Gate Charge	V <sub>CC</sub> =480V	-	31.9		nC
Q <sub>ge</sub>	Gate-Emitter Charge	V <sub>GE</sub> =15V	-	10.8		nC
Qgc	Gate-Collector Charge	Ic=15A	-	19.1		nC
t d(on)	Turn-on Delay Time		-	27	-	ns
t <sub>r</sub>	Turn-on Rise Time	V <sub>CC</sub> =400V V <sub>GE</sub> =15V	-	61	-	ns
t d(off)	Turn-off Delay Time		-	61	-	ns
t f	Turn-off Fall Time	l <sub>C</sub> =15Α  R <sub>G</sub> =15Ω	-	87	-	ns
Eon	Turn-on Switching Loss	Inductive Load T <sub>C</sub> =25 ℃	-	0.71	-	mJ
Eoff	Turn-off Switching Loss		-	0.32	-	mJ
Ets	Total Switching Loss		-	1.03	-	mJ
Cies	Input Capacitance	V <sub>CE</sub> =25V V <sub>GE</sub> =0V	-	740	-	pF
C <sub>oes</sub>	Output Capacitance		-	44	-	pF
C <sub>res</sub>	Reverse Transfer Capacitance	f = 1MHz	-	14	-	pF

## **Electrical Characteristics of Diode** (Tc=25°C unless otherwise noted)

Symbol	Parameter	Test Conditions	Min.	Тур.	Max.	Units
V <sub>F</sub>	Diode Forward Voltage	I <sub>F</sub> =15A	1	1.45	1.95	V
trr	Diode Reverse Recovery Time	V <sub>CE</sub> = 400V		74		ns
Irr	Diode peak Reverse Recovery Current	I <sub>F</sub> = 15A	•	14		Α
Qrr	Diode Reverse Recovery Charge	Rg=15 Ω	-	547		nC

#### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature



# **Typical Performance Characteristics**

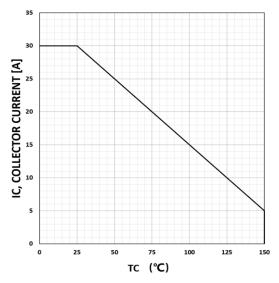


Figure 1. Maximum DC collector current VS. case temperature

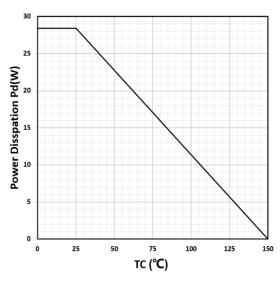


Figure 2. Power dissipation VS. case temperature

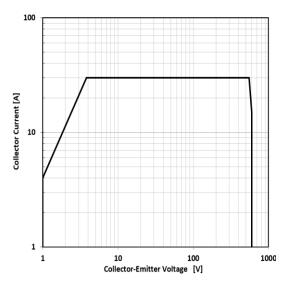


Figure 3. Reverse bias SOA, Tj=125℃,Vge=15V

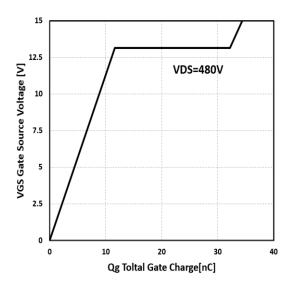


Figure4:Typical gate charge VS. VGE,IC=15A





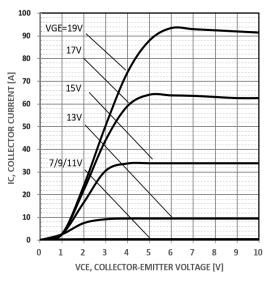


Figure 5. Typical output characteristics tp=300us Tc=25  $^{\circ}\mathrm{C}$ 

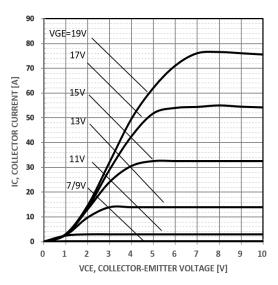


Figure 6. Typical output characteristics tp=300us Tc=150℃

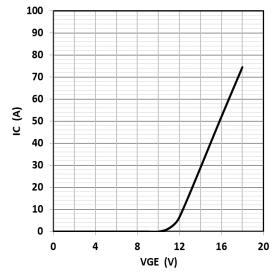


Figure 7. Typical gate threshold voltage

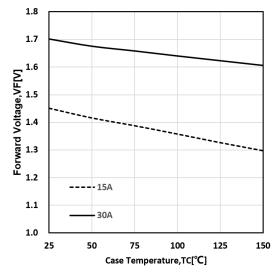


Figure 8. Typical forward voltage vs Tc





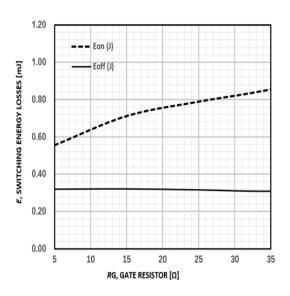


Figure9: Typical energy loss VS. Rg,TC=25°C, VCE=400V, VGE=15V ,IC=15A

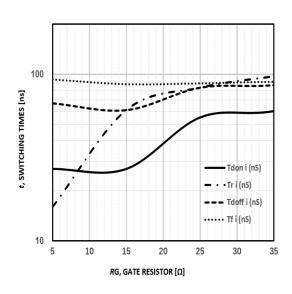


Figure 10: Typical switching time VS. Rg,TC=25°C, VCE=400V, VGE=15V ,IC=15A

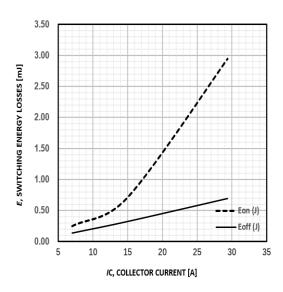


Figure11: Typical energy loss VS. IC, TC=25°C,  $\label{eq:VCE=400V} VGE=15V \ , RG=15\Omega$ 

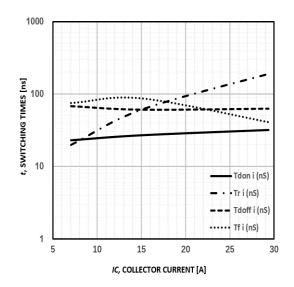


Figure 12: Typical switching time VS. IC, TC=25°C, VCE=400V, VGE=15V,RG=15 $\Omega$ 





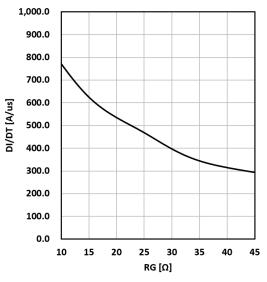


Figure 13. Typical diode di/dt vs rg  $Tc=25^{\circ}C$ VCE=400V VGE=15V IF=15A

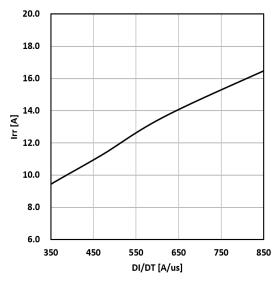


Figure 14. Typical diode irr vs di/dt Tc=25℃ VCE=400V VGE=15V IF=15A

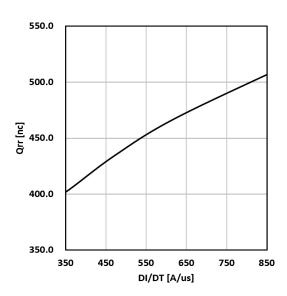


Figure 15. Typical diode Qrr vs di/dt  $Tc=25^{\circ}C$  VCE=400V VGE=15V IF=15A

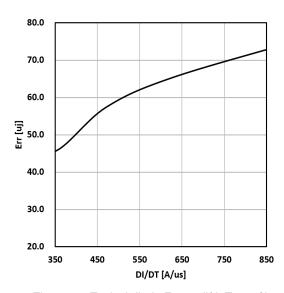


Figure 16. Typical diode Err vs di/dt Tc=25°C VCC=400V VGE=15V IF=15A



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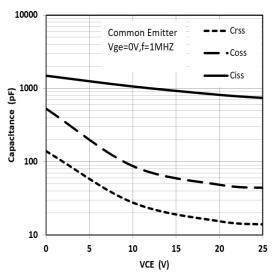


Figure17:Typical capacitance VS. VCE, VGE=0V,f=1MHz

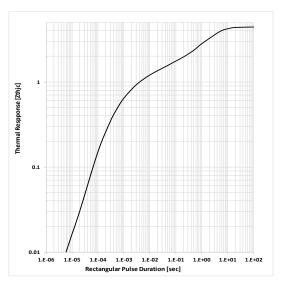
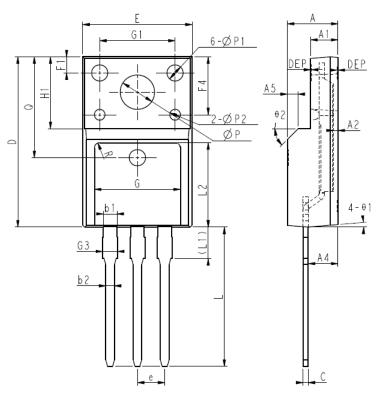


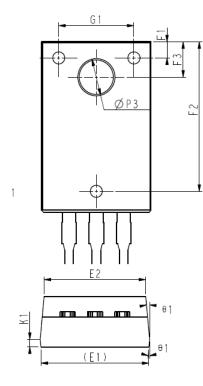
Figure 18. normalized transient thermal impedance, junction-to-case



# **Mechanical Dimensions**



COMMON DIMENSIONS



	MM			
SYMBOL	MIN	NOM	MAX	
Е	10.00	10, 16	10, 32	
B1	9, 94	10. 04	10.14	
E2	9, 36	9.46	9. 56	
A	4, 50	4.70	4, 90	
A1	2, 34	2.54	2. 74	
A2	0, 43	-	0, 48	
A4	2, 66	2.76	2. 86	
A5		1. 00REF		
С	0.45	0.50	0.60	
D	15.67	15. 87	16.07	
Q		9. 40REF		
H1		6. 70REF		
е		2. 54BSC		
ΦР		3. 18REF		
L	12.78	12.98	13.18	
L1	2.83	2.93	3.03	
L2	7.70	7.80	7.90	
ФР1	1.40	1.50	1.60	
ФР2	0.95	1.00	1.05	
ФР3		3. 45REF		
θ 1	3°	5°	7°	
θ2	-	45°	-	
DEP	0.05	0.10	0.15	
F1	1.00	1.50	2.00	
F2	13.80	13.90	14.00	
F3	3. 20	3. 30	3. 40	
F4	5. 30	5. 40	5. 50	
G	7. 80	8.00	8. 20	
G1	6. 90	7.00	7. 10	
G3	1. 25	1.35	1. 45	
b1	1. 23	1.28	1. 38	
b2	0. 75	0.80	0. 90	
K1	0. 65	0.70	0. 75	
R	0. 50REF			



#### JNG15T60FS

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